

**Product / Package Information**

<b>Package</b>	LFCSP - Sawn
<b>Body Size (mm)</b>	2 X 2 X 0.55 (1.6 X 1.0 EP)
<b>Lead Count</b>	6
<b>Terminal Finish</b>	NiPdAu

**Environmental Information**

<b>RoHS Compliant</b>	Yes
<b>High Temperature Compliant</b>	Yes
<b>Halogen Free Compliant</b>	Yes
<b>REACH SVHC Compliant</b>	Yes

**Materials Declaration**

**Molding Compound**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Other inorganic materials	Silica	60676-96-0	5.00E-03	83.25	832500	34.28		342767
Thermosets	Epoxy resin	Proprietary	3.25E-04	5.42	54200	2.23		22316
Thermosets	Phenol resin	Proprietary	2.07E-04	3.45	34500	1.42		14205
Other inorganic materials	Metal Hydroxide	Proprietary	3.25E-04	5.42	54200	2.23		22316
Others	Others	Proprietary	1.48E-04	2.46	24600	1.01		10129
<b>Subtotal</b>			<b>6.00E-03</b>	<b>100.00</b>	<b>1000000</b>	<b>41.17</b>		<b>411733</b>

**Leadframe**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Copper & its alloys	Copper	7440-50-8	5.25 E-03	96.20	962000	36.04		360433
Copper & its alloys	Nickel	7440-02-0	1.64 E-04	3.00	30000	1.12		11240
Copper & its alloys	Silicon	7440-21-3	3.55 E-05	0.65	6500	0.24		2435
Copper & its alloys	Magnesium	7439-95-4	8.19 E-06	0.15	1500	0.06		562
<b>Subtotal</b>			<b>5.46 E-03</b>	<b>100.00</b>	<b>1000000</b>	<b>37.47</b>		<b>374671</b>

**Internal / External Leadframe Plating**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Nickel & its alloys	Nickel	7440-02-0	2.97 E-04	95.0	950185	2.04		20401
Precious metals	Palladium	7440-05-3	1.27 E-05	4.1	40590	0.09		872
Precious metals	Gold	7440-57-5	2.89 E-06	0.9	9225	0.02		198
<b>Subtotal</b>			<b>3.13 E-04</b>	<b>100.00</b>	<b>1000000</b>	<b>2.15</b>		<b>21471</b>

**Bond Wires**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Precious metals	Gold	7440-57-5	6.75 E-05	100.0	1000000	0.46		4633

**Chip**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Other inorganic materials	Doped Silicon	7440-21-3	2.63 E-03	100.0	1000000	18.01		180133

**Die Attach**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Precious metals	Silver	7440-22-4	8.26 E-05	77.00	770000	0.57		5667
Other organic materials	Acrylic resin	Proprietary	7.51 E-06	7.00	70000	0.05		515
Other organic materials	Acrylate	Proprietary	5.90 E-06	5.50	55000	0.04		405
Other organic materials	Polybutadiene derivative	Proprietary	4.83 E-06	4.50	45000	0.03		331
Thermoset	Epoxy resin	Proprietary	2.68 E-06	2.50	25000	0.02		184
Other organic materials	Butadiene Copolymer	Proprietary	1.61 E-06	1.50	15000	0.01		110
Others	Additive	Proprietary	1.61 E-06	1.50	15000	0.01		110
Others	Peroxide	Proprietary	5.36 E-07	0.50	5000	0.00		37
<b>Subtotal</b>			<b>1.07 E-04</b>	<b>100.0</b>	<b>1000000</b>	<b>0.74</b>		<b>7360</b>

<b>Package Totals</b>			<b>Weight (g)</b>	<b>Percentage (%)</b>	<b>PPM</b>	<b>1000000</b>
			<b>1.46 E-02</b>	<b>100.00</b>		

Note: The information provided in this declaration are true to the best of ADI's knowledge. ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.



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